

SLCS006S - OCTOBER 1979-REVISED AUGUST 2012

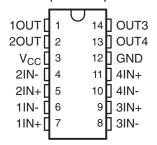
QUAD DIFFERENTIAL COMPARATORS

Check for Samples: LM139, LM239, LM339, LM139A, LM239A, LM339A, LM2901, LM2901AV, LM2901V

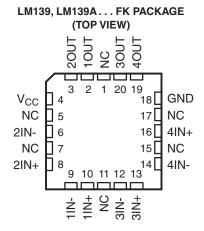
FEATURES

- Wide Supply Ranges
 - Single Supply: 2 V to 36 V (Tested to 30 V for Non-V Devices and 32 V for V-Suffix Devices)
 - Dual Supplies: ±1 V to ±18 V (Tested to ±15 V for Non-V Devices and ±16 V for V-Suffix Devices)
- Low Supply-Current Drain Independent of Supply Voltage: 0.8 mA (Typ)

LM139, LM139A... D, J, OR W PACKAGE
LM239... D, N, OR PW PACKAGE
LM239A... D PACKAGE
LM339, LM339A... D, DB, N, NS, OR PW PACKAGE
LM2901... D, N, NS, OR PW PACKAGE
(TOP VIEW)



- Low Input Bias Current: 25 nA (Typ)
- Low Input Offset Current: 3 nA (Typ) (LM139)
- Low Input Offset Voltage: 2 mV (Typ)
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: ±36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS



NC - No inter nal connection

DESCRIPTION/ORDERING INFORMATION

These devices consist of four independent voltage comparators that are designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible, as long as the difference between the two supplies is 2 V to 36 V, and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The outputs can be connected to other open-collector outputs to achieve wired-AND relationships.

The LM139 and LM139A are characterized for operation over the full military temperature range of -55°C to 125°C. The LM239 and LM239A are characterized for operation from -25°C to 125°C. The LM339 and LM339A are characterized for operation from 0°C to 70°C. The LM2901, LM2901AV, and LM2901V are characterized for operation from -40°C to 125°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



Table 1. ORDERING INFORMATION⁽¹⁾

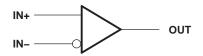
T _A	V _{IO} max AT 25°C	MAX V _{CC}	PAC	KAGE ⁽²⁾	ORDERABLE PART NUMBER	TOP-SIDE MARKING
			PDIP – N	Tube of 25	LM339N	LM339N
				Tube of 50	LM339D	
			SOIC - D	Dark of 0500	LM339DR	LM339
	- ·	00.14		Reel of 2500	LM339DRG3	
	5 mV	30 V	SOP - NS	Reel of 2000	LM339NSR	LM339
			SSOP – DB	Reel of 2000	LM339DBR	LM339
			T0005 BW	Tube of 90	LM339PW	
0°C to 70°C			TSSOP – PW	Reel of 2000	LM339PWRG3	L339
			PDIP – N	Tube of 25	LM339AN	LM339AN
				Tube of 50	LM339AD	
			SOIC – D	Reel of 2500	LM339ADR	LM339A
	2 mV	30 V	SOP – NS	Reel of 2000	LM339ANSR	LM339A
			SSOP – DB	Reel of 2000	LM339ADBR	L339A
				Tube of 90	LM339APW	
			TSSOP – PW	Reel of 2000	LM339APWR	L339A
			PDIP – N	Tube of 25	LM239N	LM239N
				Tube of 50	LM239D	
			SOIC - D		LM239DR	LM239
	5 mV	30 V	00.0	Reel of 2500	LM239DRG3	
–25°C to 85°C				Tube of 90	LM239PW	
			TSSOP – PW	Reel of 2000	LM239PWR	L239
				Tube of 50	LM239AD	
	2 mV	30 V	SOIC - D	Reel of 2500	LM239ADR	LM239A
			PDIP – N	Tube of 25	LM2901N	LM2901N
				Tube of 50	LM2901D	
			SOIC - D		LM2901DR	LM2901
	7 mV	30 V	00.0	Reel of 2500	LM2901DRG3	
	, III v	00 V	SOP – NS	Reel of 2000	LM2901NSR	LM2901
-40°C to 125°C			001 110	Tube of 90	LM2901PW	LIVIZOOT
40 0 10 120 0			TSSOP - PW	Reel of 2000	LM2901PWRG3	L2901
			SOIC - D	Reel of 2500	LM2901VQDR	L2901V
	7 mV	32 V	TSSOP – PW	Reel of 2000	LM2901VQPWR	L2901V
			SOIC - D	Reel of 2500	LM2901AVQDR	L2901AV
	2 mV	32 V	TSSOP – PW	Reel of 2000	LM2901AVQPWR	L2901AV
			CFP – W	Tube of 25	LM139W	LM139W
			CDIP – J			
	5 mV	30 V	LCCC – FK	Tube of 25 Tube of 55	LM139J	LM139J LM139FK
-55°C to 125°C —	SIIIV	30 V	LUCU - FK		LM139FK	LIVITOSEN
			SOIC - D	Tube of 50	LM139D	LM139
			CED W	Reel of 2500	LM139DR	I M420AW
			CFP – W	Tube of 25	LM139AW	LM139AW
	0>/	20.14	CDIP – J	Tube of 25	LM139AJ	LM139AJ
	2 mV	30 V	LCCC – FK	Tube of 55	LM139AFK	LM139AFK
			SOIC - D	Tube of 50	LM139AD	LM139AD
				Reel of 2500	LM139ADR	

⁽¹⁾ For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI web site at www.ti.com.

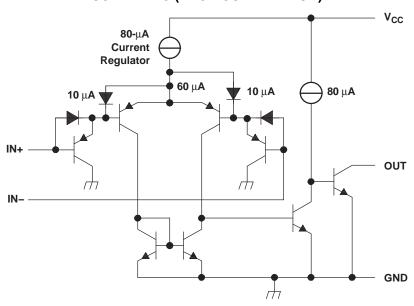
⁽²⁾ Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



SYMBOL (EACH COMPARATOR)



SCHEMATIC (EACH COMPARATOR)



All current values shown are nominal.

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ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

NSTRUMENTS

www.ti.com

			MIN	MAX	UNIT
V_{CC}	Supply voltage ⁽²⁾			36	V
V_{ID}	Differential input voltage (3)			±36	V
V_{I}	Input voltage range (either input)		-0.3	36	V
Vo	Output voltage			36	V
Io	Output current			20	mA
	Duration of output short circuit to ground ⁽⁴⁾		U	nlimited	
		D package		86	
		DB package		96	
θ_{JA}	Package thermal impedance, junction to free air (5) (6)	N package		80	°C/W
		NS package		76	
		PW package		113	
		FK package		5.61	
θ_{JC}	Package thermal impedance, junction to case (7) (8)	J package		15.05	°C/W
		W package		14.65	
T _J	Operating virtual-junction temperature			150	°C
	Case temperature for 60 s	FK package		260	°C
	Lead temperature 1,6 mm (1/16 in) from case for 60 s	J package		300	°C
T _{stg}	Storage temperature range	·	-65	150	°C

Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

All voltage values, except differential voltages, are with respect to network ground.

Differential voltages are at IN+ with respect to IN-.

Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.

The package thermal impedance is calculated in accordance with MIL-STD-883.

Short circuits from outputs to V_{CC} can cause excessive healing and eventual destruction. Maximum power dissipation is a function of T_J (max), θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J \text{ (max)} - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can affect reliability. The package thermal impedance is calculated in accordance with JESD 51-7. Maximum power dissipation is a function of $T_J \text{ (max)}$, θ_{JC} , and T_C . The maximum allowable power dissipation at any allowable case

temperature is $P_D = (T_J (max) - T_C)/\theta_{JC}$. Operating at the absolute maximum T_J of 150°C can affect reliability.



ELECTRICAL CHARACTERISTICS

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	DADAMETED	TEST CON	NDITIONS ⁽¹⁾	T _A (2)	LM	139		LM1	39A		UNIT
	PARAMETER	TEST CON	NUTTONS	IA (-/	MIN	TYP	MAX	MIN	TYP	MAX	UNII
		$V_{CC} = 5 \text{ V to}$		25°C		2	5		1	2	
V _{IO}	Input offset voltage	$V_{IC} = V_{ICR} m$ $V_{O} = 1.4 V$	in,	Full range			9			4	mV
	Input offeet ourrent	\/ 4.4.\/		25°C		3	25		3	25	nA
I _{IO}	Input offset current	$V_0 = 1.4 \text{ V}$		Full range			100			100	ΠA
	Input bias current	V _O = 1.4 V		25°C		-25	-100		-25	-100	nA
I _{IB}	input bias current	V _O = 1.4 V		Full range			-300			-300	IIA
V	Common-mode input-			25°C	0 to V _{CC} - 1.5			0 to V _{CC} - 1.5			V
V _{ICR}	voltage range ⁽³⁾			Full range	0 to V _{CC} - 2			0 to V _{CC} - 2			V
A _{VD}	Large-signal differential- voltage amplification	$V_{CC+} = \pm 7.5$ $V_{O} = -5 \text{ V to}$		25°C		200		50	200		V/mV
	Lligh lovel output ourrent	\/ 1\/	V _{OH} = 5 V	25°C		0.1			0.1		nA
I _{OH}	High-level output current	$V_{ID} = 1 V$	V _{OH} = 30 V	Full range			1			1	μΑ
\/	Low lovel output voltage	\/ 1\/		25°C		150	400		150	400	mV
V _{OL}	Low-level output voltage	$V_{ID} = -1 V$,	$I_{OL} = 4 \text{ mA}$	Full range			700			700	IIIV
I _{OL}	Low-level output current	$V_{ID} = -1 V$	V _{OL} = 1.5 V	25°C	6	16		6	16		mA
I _{CC}	Supply current (four comparators)	V _O = 2.5 V,	No load	25°C		0.8	2		0.8	2	mA

- (1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
- (2) Full range (MIN to MAX) for LM139 and LM139A is –55°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.
- (3) The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} 1.5 V; however, one input can exceed V_{CC}, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.

SWITCHING CHARACTERISTICS

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST C	ONDITIONS	LM139 LM139A TYP	UNIT
Dannara tima	R _I connected to 5 V through 5.1 kΩ,	100-mV input step with 5-mV overdrive	1.3	
Response time	R_L connected to 5 V through 5.1 k Ω , C_L = 15 pF ⁽¹⁾ (2)	TTL-level input step	0.3	μs

- (1) C_L includes probe and jig capacitance.
- (2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



ELECTRICAL CHARACTERISTICS

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	PARAMETER	TEST CON	DITIONS ⁽¹⁾	T _A (2)		239 339			239A 339A		UNIT
					MIN	TYP	MAX	MIN	TYP	MAX	
		V _{CC} = 5 V to 3		25°C		2	5		1	3	
V _{IO}	Input offset voltage	$V_{IC} = V_{ICR} \text{ min}$ $V_{O} = 1.4 \text{ V}$,	Full range			9			4	mV
	Innut offeet ourrent	V 4.4.V		25°C		5	50		5	50	~ ^
I _{IO}	Input offset current	$V_0 = 1.4 \text{ V}$		Full range			150			150	nA
	Input bigg gurrent	V _O = 1.4 V		25°C		-25	-250		-25	-250	nA
I _{IB}	Input bias current	V _O = 1.4 V		Full range			-400			-400	ΠA
.,	Common-mode input-			25°C	0 to V _{CC} - 1.5			0 to V _{CC} - 1.5			V
V _{ICR}	voltage range ⁽³⁾			Full range	0 to V _{CC} - 2			0 to V _{CC} - 2			V
A _{VD}	Large-signal differential- voltage amplification	V_{CC} = 15 V, V_{O} = 1.4 V to 1 R_{L} ≥ 15 k Ω to	1.4 V, V _{CC}	25°C	50	200		50	200		V/mV
	Lligh level output ourrent	V 4.V	V _{OH} = 5 V	25°C		0.1	50		0.1	50	nA
I _{OH}	High-level output current	$V_{ID} = 1 V$	$V_{OH} = 30 \text{ V}$	Full range			1			1	μΑ
\/	Low lovel output voltage	V - 1 V	- 4 mΛ	25°C		150	400		150	400	mV
V _{OL}	Low-level output voltage	$V_{ID} = -1 V$,	$I_{OL} = 4 \text{ mA}$	Full range			700			700	IIIV
I _{OL}	Low-level output current	$V_{ID} = -1 V$,	V _{OL} = 1.5 V	25°C	6	16		6	16		mA
I _{CC}	Supply current (four comparators)	V _O = 2.5 V,	No load	25°C		0.8	2		0.8	2	mA

⁽¹⁾ All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

SWITCHING CHARACTERISTICS

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

PARAMETER	TEST CON	DITIONS	LM239 LM239A LM339 LM339A	UNIT
		ITP		
Pagagonag tima	R_L connected to 5 V through 5.1 kΩ, $C_L = 15 \text{ pF}^{(1)}$ (2)	100-mV input step with 5-mV overdrive	1.3	
Response time	$C_L = 15 \text{ pF}^{(1)} (2)$	TTL-level input step	0.3	μs

(1) C_L includes probe and jig capacitance.

(2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

⁽²⁾ Full range (MIN to MAX) for LM239/LM239A is -25°C to 85°C, and for LM339/LM339A is 0°C to 70°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

⁽³⁾ The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V; however, one input can exceed V_{CC}, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to 30 V without damage.



ELECTRICAL CHARACTERISTICS

at specified free-air temperature, V_{CC} = 5 V (unless otherwise noted)

	DARAMETER	TEST SOME	NTIONO(1)	- (2)	LM	2901		
	PARAMETER	TEST COND	OTTIONS(1)	T _A ⁽²⁾	MIN	TYP	MAX	UNIT
			Non A devises	25°C		2	7	
	Leavet office to college	$V_{IC} = V_{ICR} \min$	Non-A devices	Full range			15	
V_{IO}	Input offset voltage	$V_O = 1.4 \text{ V},$ $V_{CC} = 5 \text{ V to MAX}^{(3)}$	A	25°C		1	2	mV
			A-suffix devices	Full range			4	
	Innut offeet ourrent	V 4.4V		25°C		5	50	~ A
I _{IO}	Input offset current	V _O = 1.4 V		Full range			200	nA
	lancet bina accument	V 4.4.V		25°C		-25	-250	- 1
I _{IB}	Input bias current	V _O = 1.4 V		Full range			-500	nA
V	Common-mode input-			25°C	0 to V _{CC} - 1.5			V
V _{ICR}	voltage range (4)			Full range	0 to V _{CC} - 2			V
A _{VD}	Large-signal differential- voltage amplification	$V_{CC} = 15 \text{ V}, V_{O} = 1.4 \text{ V}$ $R_{L} \ge 15 \text{ k}\Omega \text{ to } V_{CC}$	to 11.4 V,	25°C	25	100		V/mV
	High lavel autout august	V 4.V	V _{OH} = 5 V	25°C		0.1	50	nA
I _{OH}	High-level output current	V _{ID} = 1 V	$V_{OH} = V_{CC} MAX^{(3)}$	Full range			1	μΑ
			Non-V devices	0500		150	500	
V_{OL}	Low-level output voltage	$V_{ID} = -1 V$, $I_{OI} = 4 \text{ mA}$	V-suffix devices	25°C		150	400	mV
		IOL - 4 IIIA	All devices	Full range			700	
I _{OL}	Low-level output current	$V_{ID} = -1 V$,	V _{OL} = 1.5 V	25°C	6	16		mA
	Supply current	V _O = 2.5 V,	V _{CC} = 5 V	25°C		0.8	2	A
I _{CC}	(four comparators)	No load	$V_{CC} = MAX^{(3)}$	25°C		1	2.5	mA

⁽¹⁾ All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

SWITCHING CHARACTERISTICS

 $V_{CC} = 5 \text{ V}, T_A = 25^{\circ}\text{C}$

DADAMETED	TEST OF	ONDITIONS	LM2901	LINUT
PARAMETER	TEST CO	ONDITIONS	TYP	UNIT
Doonanaa tima	R_L connected to 5 V through 5.1 kΩ, C_L = 15 pF ⁽¹⁾ (2)	100-mV input step with 5-mV overdrive	1.3	
Response time	$C_L = 15 \text{ pF}^{(1)}$ (2)	TTL-level input step	0.3	μs

⁽¹⁾ C_L includes probe and jig capacitance.

⁽²⁾ Full range (MIN to MAX) for LM2901 is -40°C to 125°C. All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

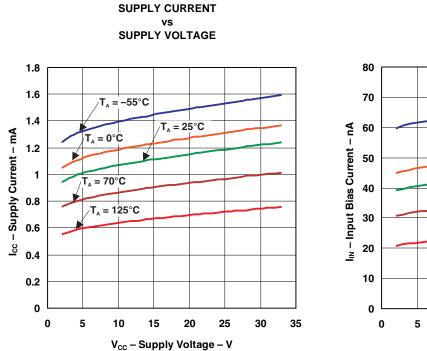
⁽³⁾ V_{CC} MAX = 30 V for non-V devices, and 32 V for V-suffix devices

⁽⁴⁾ The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is V_{CC+} – 1.5 V; however, one input can exceed V_{CC}, and the comparator will provide a proper output state as long as the other input remains in the common-mode range. Either or both inputs can go to V_{CC} MAX without damage.

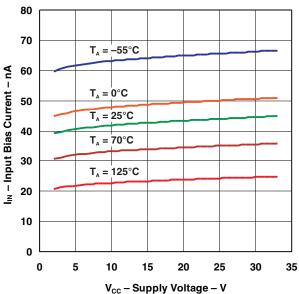
⁽²⁾ The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.



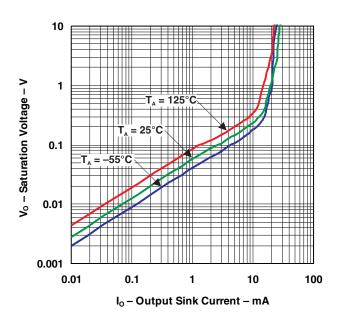
TYPICAL CHARACTERISTICS



INPUT BIAS CURRENT vs SUPPLY VOLTAGE



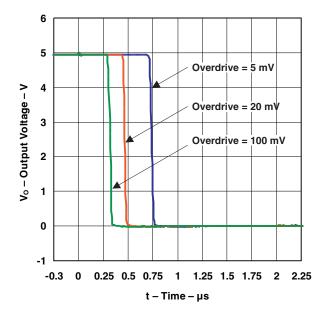
OUTPUT SATURATION VOLTAGE



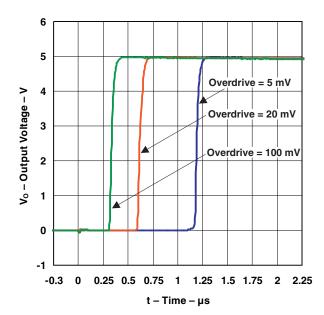


TYPICAL CHARACTERISTICS (continued)

RESPONSE TIME FOR VARIOUS OVERDRIVES NEGATIVE TRANSITION



RESPONSE TIME FOR VARIOUS OVERDRIVES POSITIVE TRANSITION



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REVISION HISTORY

Changes from Revision R (July 2010) to Revision S					
•	Updated ORDERING INFORMATION table.		2		

Submit Documentation Feedback





4-Dec-2014

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)	0010			-	(2)	(6)	(3)		(4/5)	
5962-7700801VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-7700801VC A LM139JQMLV	Samples
5962-87739012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 87739012A LM139AFKB	Samples
5962-8773901CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8773901CA LM139AJB	Samples
5962-8773901DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8773901DA LM139AWB	Samples
5962-9673802V9B	ACTIVE	XCEPT	KGD	0	100	TBD	Call TI	N / A for Pkg Type	-55 to 125		Samples
5962-9673802VCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-9673802VC A LM139AJQMLV	Samples
77008012A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	77008012A LM139FKB	Samples
7700801CA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700801CA LM139JB	Samples
7700801DA	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700801DA LM139WB	Samples
JM38510/11201BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510 /11201BCA	Samples
LM139AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139A	Samples
LM139AFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	5962- 87739012A LM139AFKB	Samples
LM139AJ	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	LM139AJ	Samples





Orderable Device	Status	Package Type	Package	Pins	Package	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM139AJB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8773901CA LM139AJB	Samples
LM139AN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	-55 to 125		
LM139AW	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	LM139AW	Samples
LM139AWB	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	5962-8773901DA LM139AWB	Samples
LM139D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM139DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM139DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM139DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-55 to 125	LM139	Samples
LM139FK	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	LM139FK	Samples
LM139FKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	-55 to 125	77008012A LM139FKB	Samples
LM139J	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	LM139J	Samples
LM139JB	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700801CA LM139JB	Samples
LM139N	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	-55 to 125		
LM139W	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	LM139W	Samples
LM139WB	ACTIVE	CFP	W	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	7700801DA LM139WB	Samples
LM239AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples





Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM239ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239A	Samples
LM239AN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	-25 to 85		
LM239D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	LM239	Samples
LM239N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU CU SN	N / A for Pkg Type	-25 to 85	LM239N	Samples
LM239NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-25 to 85	LM239N	Samples
LM239PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM239PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-25 to 85	L239	Samples
LM2901AVQDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901AVQDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples





Orderable Device	Status	Package Type		Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM2901AVQPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901AVQPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901AV	Samples
LM2901D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Sample
LM2901DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Samples
LM2901DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	LM2901	Sample
LM2901DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Sample
LM2901N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2901N	Sample
LM2901NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	-40 to 125	LM2901N	Sample
LM2901NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Sample
LM2901NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	LM2901	Sample
LM2901PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901	Sample
LM2901PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901	Sample
LM2901PWLE	OBSOLETI	TSSOP	PW	14		TBD	Call TI	Call TI	-40 to 125		
LM2901PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	-40 to 125	L2901	Sample
LM2901PWRG3	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 125	L2901	Sample





Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM2901PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901	Samples
LM2901QD	OBSOLETE	SOIC	D	14		TBD	Call TI	Call TI	-40 to 125		
LM2901QN	OBSOLETE	PDIP	N	14		TBD	Call TI	Call TI	-40 to 125		
LM2901VQDR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM2901VQDRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM2901VQPWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM2901VQPWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 125	L2901V	Samples
LM339AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339ADBRG4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ADRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339AN	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU CU SN	N / A for Pkg Type	0 to 70	LM339AN	Samples
LM339ANE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM339AN	Samples
LM339ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples
LM339ANSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339A	Samples



Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM339APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339A	Samples
LM339D	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DBLE	OBSOLETE	SSOP	DB	14		TBD	Call TI	Call TI	0 to 70		
LM339DBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DG4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DRG3	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339DRG4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339N	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU CU SN	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NE3	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU SN	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NE4	ACTIVE	PDIP	N	14	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type	0 to 70	LM339N	Samples
LM339NSLE	OBSOLETE	so so	NS	14		TBD	Call TI	Call TI	0 to 70		



PACKAGE OPTION ADDENDUM

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Orderable Device	Status	Package Type	_	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM339NSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339NSRG4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	LM339	Samples
LM339PW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWLE	OBSOLETI	TSSOP	PW	14		TBD	Call TI	Call TI	0 to 70		
LM339PWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU CU SN	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWRG3	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339PWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	0 to 70	L339	Samples
LM339Y	OBSOLETI			0		TBD	Call TI	Call TI	0 to 70		
M38510/11201BCA	ACTIVE	CDIP	J	14	1	TBD	A42	N / A for Pkg Type	-55 to 125	JM38510 /11201BCA	Samples

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

PACKAGE OPTION ADDENDUM



4-Dec-2014

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF LM139, LM139-SP, LM239A, LM2901, LM2901AV, LM2901V:

Catalog: LM139

Automotive: LM239A-Q1, LM2901-Q1, LM2901AV-Q1, LM2901V-Q1

Enhanced Product: LM239A-EP

Space: LM139-SP

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects
- Enhanced Product Supports Defense, Aerospace and Medical Applications
- Space Radiation tolerant, ceramic packaging and qualified for use in Space-based application

PACKAGE MATERIALS INFORMATION

www.ti.com 3-Dec-2014

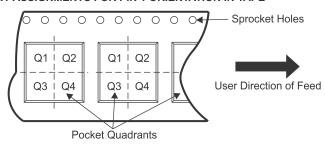
TAPE AND REEL INFORMATION



TAPE DIMENSIONS + K0 - P1 - B0 W Cavity - A0 -

A0	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM139ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM139DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM239DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM239DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM239PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901AVQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901AVQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM2901DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM2901DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM2901NSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1



PACKAGE MATERIALS INFORMATION

www.ti.com 3-Dec-2014

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM2901PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901VQPWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM2901VQPWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339ADBR	SSOP	DB	14	2000	330.0	16.4	8.2	6.6	2.5	12.0	16.0	Q1
LM339ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339ADR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339ADR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM339ADRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339ANSR	SO	NS	14	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1
LM339APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339APWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339DR	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM339DRG3	SOIC	D	14	2500	330.0	16.8	6.5	9.5	2.3	8.0	16.0	Q1
LM339DRG4	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
LM339PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339PWR	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339PWRG3	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1
LM339PWRG4	TSSOP	PW	14	2000	330.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

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*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM139ADR	SOIC	D	14	2500	367.0	367.0	38.0
LM139DR	SOIC	D	14	2500	367.0	367.0	38.0
LM239ADR	SOIC	D	14	2500	333.2	345.9	28.6
LM239ADR	SOIC	D	14	2500	367.0	367.0	38.0
LM239DR	SOIC	D	14	2500	367.0	367.0	38.0
LM239DR	SOIC	D	14	2500	364.0	364.0	27.0
LM239DR	SOIC	D	14	2500	333.2	345.9	28.6
LM239DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM239DRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM239PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901AVQPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901AVQPWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901DR	SOIC	D	14	2500	333.2	345.9	28.6
LM2901DR	SOIC	D	14	2500	367.0	367.0	38.0
LM2901DR	SOIC	D	14	2500	364.0	364.0	27.0
LM2901DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM2901DRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM2901NSR	SO	NS	14	2000	367.0	367.0	38.0
LM2901PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901PWR	TSSOP	PW	14	2000	364.0	364.0	27.0



PACKAGE MATERIALS INFORMATION

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Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM2901PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM2901PWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901VQPWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM2901VQPWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0
LM339ADBR	SSOP	DB	14	2000	367.0	367.0	38.0
LM339ADR	SOIC	D	14	2500	367.0	367.0	38.0
LM339ADR	SOIC	D	14	2500	333.2	345.9	28.6
LM339ADR	SOIC	D	14	2500	364.0	364.0	27.0
LM339ADRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM339ANSR	SO	NS	14	2000	367.0	367.0	38.0
LM339APWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM339APWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM339DR	SOIC	D	14	2500	333.2	345.9	28.6
LM339DR	SOIC	D	14	2500	367.0	367.0	38.0
LM339DR	SOIC	D	14	2500	364.0	364.0	27.0
LM339DRG3	SOIC	D	14	2500	364.0	364.0	27.0
LM339DRG4	SOIC	D	14	2500	333.2	345.9	28.6
LM339PWR	TSSOP	PW	14	2000	364.0	364.0	27.0
LM339PWR	TSSOP	PW	14	2000	367.0	367.0	35.0
LM339PWRG3	TSSOP	PW	14	2000	364.0	364.0	27.0
LM339PWRG4	TSSOP	PW	14	2000	367.0	367.0	35.0

14 LEADS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package is hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
- E. Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

W (R-GDFP-F14)

CERAMIC DUAL FLATPACK



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification only.
- E. Falls within MIL STD 1835 GDFP1-F14



FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M—1994.
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
- E. Falls within JEDEC MO-153



PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Publication IPC-7351 is recommended for alternate designs.
- D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
- E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

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